

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79703

Hisayuki MIKI, et al.

Appln. No.: 10/586,849

Group Art Unit: 2811

Confirmation No.: 3462

Examiner: Unknown

Filed: July 20, 2006

For: GALLIUM NITRIDE-BASED COMPOUND SEMICONDUCTOR MULTILAYER
STRUCTURE AND PRODUCTION METHOD THEREOF

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

ATTN: Office of Initial Patent Examination
Filing Receipt Correction
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and
request the following correction:

Assignment for Published Patent Application

SHOWA DENKO K.K.

Verification for the requested correction is indicated on the Executed Assignment
Document filed July 20, 2006.

Respectfully submitted,



Abraham J. Rosner
Registration No. 33,276

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: April 24, 2007



UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371(a) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	TOT CLMS	IND CLMS
10/586,849	07/20/2006	2811	1750	Q79703	37	2

CONFIRMATION NO. 3482

23373
 SUGHRUE MION, PLLC
 2100 PENNSYLVANIA AVENUE, N.W.
 SUITE 800
 WASHINGTON, DC 20037

DOCKETED

APR 04 2007

FILING RECEIPT



0C000000023131830

Date Mailed: 03/30/2007

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Hisayuki Miki, Chiba, JAPAN;
 Tetsuo Sakurai, Chiba, JAPAN;
 Hitoshi Takeda, Chiba, JAPAN;

ASSIGNMENT FOR PUBLISHED PATENT APPLICATION

SHOWA DENKO K.K.

Power of Attorney: The patent practitioners associated with Customer Number 23373.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP05/01642 01/28/2005
 which claims benefit of 60/541,069 02/03/2004

Foreign Applications

JAPAN 2004-021479 01/29/2004

If Required, Foreign Filing License Granted: 03/27/2007

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/586,849**

Projected Publication Date: 07/05/2007

Non-Publication Request: No

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert
ASSIGNEE's
Name(s)
Address(es))

SHOMA DENKO K.K.

13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 105-8518, Japan

(Title of
Invention)

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest in the invention entitled

GALLIUM NITRIDE-BASED COMPOUND SEMICONDUCTOR MULTILAYER STRUCTURE
AND PRODUCTION METHOD THEREOF

relating to International Patent Application PCT/JP 2005/001642 and/or for which application for Letter Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date
of execution
of application,
if not
concurrent)

(a) executed on _____

(b) filed on _____
Serial No. _____

_____ is hereby authorized to insert in (b) the specified date, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, reissue, extension or prosecution application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interferences, claims, examination, or public use proceedings, and in any litigation or other legal proceedings which may arise or be desired in relation to them, such acts to include but not be limited to executing all papers, including expense engagements and declarations, taking all required oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1. Hisayuki Miki Hisayuki Miki May 22, 2006
(SIGNATURE) (TYPE NAME) (DATE)

2. Tetsuo Sakurai Tetsuo Sakurai May 22, 2006
(SIGNATURE) (TYPE NAME) (DATE)

3. Hitoshi Takeda Hitoshi Takeda May 22, 2006
(SIGNATURE) (TYPE NAME) (DATE)

4. _____ (SIGNATURE) (TYPE NAME) (DATE)

5. _____ (SIGNATURE) (TYPE NAME) (DATE)

6. _____ (SIGNATURE) (TYPE NAME) (DATE)

7. _____ (SIGNATURE) (TYPE NAME) (DATE)

8. _____ (SIGNATURE) (TYPE NAME) (DATE)